

56W Active Clamp Forward for Telecom Apps - lowest noise & constant load current

- reflected input ripple <math><50mV_{pp}</math>
- output ripple voltage <math><50mV_{pp}</math>

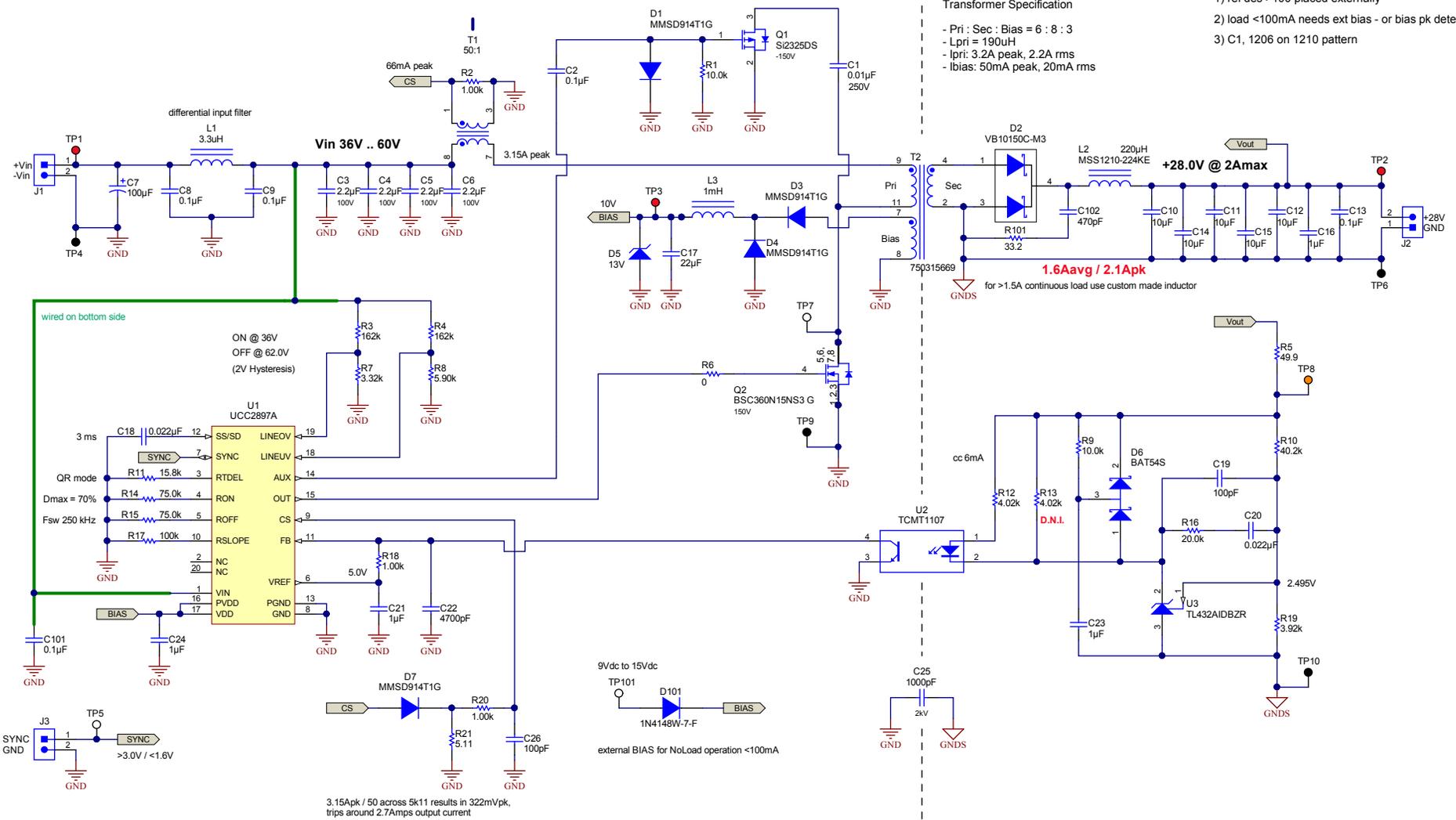
Revision History	
Revision	Notes
A	* preliminary
B	total redesign of error amp

NOTES:

- ref des >100 placed externally
- load <math><100mA</math> needs ext bias - or bias pk detection
- C1, 1206 on 1210 pattern

Transformer Specification

- Pri : Sec = Bias = 6 : 8 : 3
- Lpri = 190uH
- Lpri: 3.2A peak, 2.2A rms
- lbias: 50mA peak, 20mA rms



3.15Apk / 50 across 5K11 results in 322mVpk, trips around 2.7Amps output current

9Vdc to 15Vdc
TP101
D101
1N4148W-7-F
external BIAS for NoLoad operation <math><100mA</math>

Designed for: Public Release	Mod. Date: 9/4/2015
Project Title: Active Clamp Forward	
Number: PMP10202	Rev: B
SVN Rev: Version control disabled	Assembly Variant: [No Variations]
Drawn By: K.Nielson	File: PMP10202RevB.SchDoc
Engineer: B.Geck	Contact: http://www.ti.com/support

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